

MicroTech 2023 Annual Conference

“Advanced Packaging and Technology Trends”

University of Strathclyde, Technology & Innovation Centre

99 George Street, Glasgow, G1 1RD

Thursday 30th March 2023



Highlights

- Prototype IC Packaging*
- Packaging for Harsh Environments*
- Quantum, Power, Microwave and mmWave Packaging*
- AI in Reliability Analysis*
- Electronics in Healthcare*
- Sustainable Assembly*

[Register Here](#)

Registration Prices

	<i>Delegates</i>
<i>IMAPS Member</i>	85
<i>IMAPS Student</i>	30
<i>Non member</i>	155
<i>Corporate Member Exhibitor</i>	385
<i>Non-Member Exhibitor</i>	585

Prices - £ exclude VAT

“Where Industry and Academia Meets”

MicroTech 2023 is the **Annual IMAPS-UK Conference** which, this year, focuses on **Advanced Packaging and Technology Trends**. This In-Person Conference combines invited Keynotes, and Presentations from leading Companies and Research Institutions and the opportunity to network with the presenters, exhibitors and other attendees.

MicroTech 2023 will provide examples of the implementation of advanced packaging technologies in challenging applications, the development of sustainable materials and processes and latest advances in the assessment of quality and reliability. Advanced Packaging Technologies will not only be expected to demonstrate enhanced performance, but also improved efficiency, reduced thermal impact and overall life cycle cost benefits.

MicroTech 2023 aims to provide Delegates with an opportunity to learn from and network with leading Industry Experts as they share their experiences, developments and opportunities.



Provisional Conference Agenda:

08:30 Registration, Exhibition and Networking

09:30 Introduction to IMAPS-UK and MicroTech 2023

09:45 Session One – Advanced Packaging and Technology

Trends:

- **Keynote Presentation: Advanced, Affordable. ASAP: Prototype IC Packaging Requirements for the post wirebond age – John Wood, Silicon Contact**
- **Packaging Challenges for Quantum Technologies – Andrew Robertson and Liam Moroney, Bay Photonics**
- **Trends to Advanced Packaging for Power Electronics – Andy Longford, Panda Europe**

10:50 Exhibitor Introductions

11:00 Break: Exhibition and Networking

11:30 Session Two: Extreme Packaging and Case Studies

- **Novel Form Factors and Encapsulation for Electronics in Healthcare - Simon Johnson, CPI**
- **Challenges in High Power, Highly Integrated Microwave and mmWave Packaging – Tudor Williams, Filtronic**
- **Deposition of Fine Pitch Indium Bump for Fabrication of Radiation Detectors – Andreas Schneider and Navid Ghorbanian, STFC, Harwell**

12:30 IMAPS-UK AGM

13:00 Lunch: Exhibition and Networking

13:45 Session Three: Reliability and Analysis

- **Keynote Presentation: Plastic Encapsulation for Harsh Environments – Matt Booker and Szymon Bednarski, Alter Technology UK**
- **AI and Microelectronic Reliability – Suzanne Costello, MCS Group**

14:30 Break: Exhibition and Networking

14:45 Session Four: New Materials and Manufacturing Techniques

- **Sustainable Silver Circuitry/Sensor Production using Ink-Jetting and Laser Writing Methods – Thomas Jones, University of Dundee**
- **Highly Conductive Micropaths made from Assembled 1D Particle Structures – Yaroslav Harkavyi, AMU**
- **Laser Assisted Die Bonding using Nano-silver Material – B Bhandari and C Wang, Heriot Watt University**

15:45 Closing Remarks from Conference Chair

16:00 Depart

Registration for MicroTech 2023

Delegates will receive a **Conference Booklet (PDF)** containing details of the **Presentations and Speakers** and of the **Exhibitors** at **MicroTech 2023**. The **presentations** will be available to **download from the IMAPS-UK website** after the event.

MicroTech 2023 Sponsor

Alter Technology UK Ltd:

- **Microelectronics and Optoelectronics package design and assembly services from fast prototyping to production**
- **UK Plastic Packaging Line**
- **Factory Visit Opportunity at Livingston plant on afternoon of Wednesday 29th March 2023 – contact office@imaps.org.uk for more details.**

Exhibitors at MicroTech 2023

The following companies are exhibiting at **MicroTech 2023**:

- **Accelonix Ltd** – Specialist equipment sales and support for Microelectronics, Battery and PCB Assembly
- **DISCO Hi-Tec Europe** – Semiconductor Dicing and Grinding solutions
- **Gen3** – Manufacturer and Distributor of Test and Measurement Equipment
- **Inseto** – Manufacturing Equipment, Assembly Materials and Adhesives

Additional Exhibitor spaces are available, contact office@imaps.org.uk for more details.

The Venue

Technology and Innovation Centre,
University of Strathclyde,
99 George Street,
Glasgow,
G1 1RD
United Kingdom
More Information [HERE](#)